# 100V, 80A, 6.4mΩ N-channel Power SGT MOSFET

## JMSL1010PK

#### **Features**

- Excellent R<sub>DS(ON)</sub> and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

### **Applications**

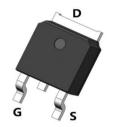
- Load Switch
- PWM Application
- Power Management

### **Product Summary**

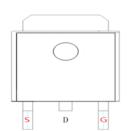
Parameters	Value	Unit
$V_{DSS}$	100	V
$V_{GS(th)\_Typ}$	1.6	V
$I_{D}(@V_{GS}=10V)$	80	Α
$R_{DS(ON)\_Typ}(@V_{GS}=10V$	6.4	mΩ
$R_{DS(ON)\_Typ}(@V_{GS}=4.5V$	8.1	mΩ



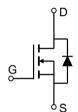




TO-252-3L(DPAK) Top



**Pin Assignment** 



**Schematic Diagram** 

#### **Ordering Information**

Device	Marking	MSL	Form	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
JMSL1010PK	L1010P	3	Tape&Reel	TO-252-3L	13"	2500	25000

### Absolute Maximum Ratings (@ T<sub>C</sub> = 25°C unless otherwise specified)

	<b>5</b> ,		. ,	
Symbol	Parameter		Value	Unit
V <sub>DS</sub>	Drain-to-Source Voltage	Drain-to-Source Voltage		V
$V_{GS}$	Gate-to-Source Voltage		±20	V
ı	Continuous Drain Current	$T_C = 25^{\circ}C$	80	Λ
I <sub>D</sub>	Continuous Drain Current	$T_C = 100$ °C	56	— A
I <sub>DM</sub>	Pulsed Drain Current (1)	_	Refer to Fig.4	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energ	gy <sup>(2)</sup>	133	mJ
P <sub>D</sub>	Dower Discipation	$T_C = 25^{\circ}C$	101	w
LD	Power Dissipation	$T_C = 100$ °C	40	VV
$T_{J}$ , $T_{STG}$	Junction & Storage Temperature	Range	-55 to 150	°C

#### **Thermal Characteristics**

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	39	°C/W
Raic	Thermal Resistance, Junction to Case	1.2	C/VV



## **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

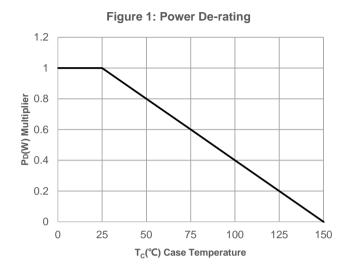
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics				l.	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, \ V_{GS} = 0 V$	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	1.1	1.6	2.1	V
D	Ctatic Duning Courses ON Designation of (4)	$V_{GS} = 10V, I_D = 20A$	-	6.4	8.4	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 4.5V, I_D = 15A$	-	8.1	10.5	mΩ
Dynami	c Characteristics					
$R_{g}$	Gate Resistance	f = 1MHz	-	2.0	-	Ω
C <sub>iss</sub>	Input Capacitance		-	1872	-	pF
C <sub>oss</sub>	Output Capacitance		-	731	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	22	-	pF
$Q_g$	Total Gate Charge	.,	-	33	-	nC
$Q_{gs}$	Gate Source Charge	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	-	6	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		nC			
Switchi	ng Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime		-	10	-	ns
t <sub>r</sub>	Turn-On Rise Time	. ==	-	20	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime	$I_{D}$ = 20A, $R_{GEN}$ = 6.2 $\Omega$	-	40	-	ns
t <sub>f</sub>	Turn-Off Fall Time	] [	-	54	-	ns
Body D	iode Characteristics					
I <sub>S</sub>	Maximum Continuous Body Diode Forward	Current	-	-	80	Α
I <sub>SM</sub>	Maximum Pulsed Body Diode Forward Current		-	-	319	Α
V <sub>SD</sub>	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 15A$	-	_	1.2	V
trr	Body Diode Reverse Recovery Time	L = 15A di/dt = 100A/vs	-	40	-	ns
Qrr	Body Diode Reverse Recovery Charge	- IF = 15A, al/at = 100A/us	-	34.9	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- $2.~E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=50V,~V_G=10V,~R_G=25ohm,~L=0.5mH,~I_{AS}=13.7A,~V_{DD}=0V~during~time~in~avalanche.$
- 3.  $\rm R_{\rm \theta JA}$  is measured with the device mounted on a 1inch  $^{2}$  pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.



# **Typical Performance Characteristics**



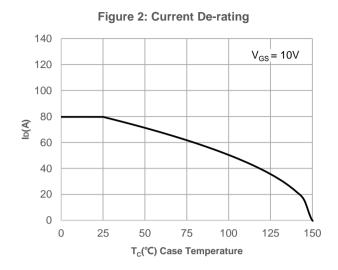
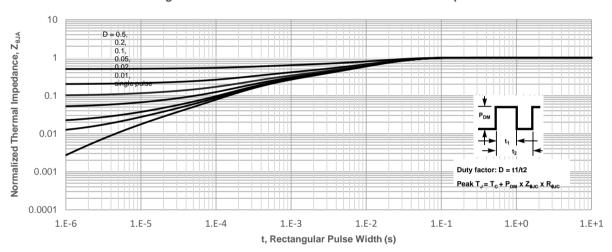
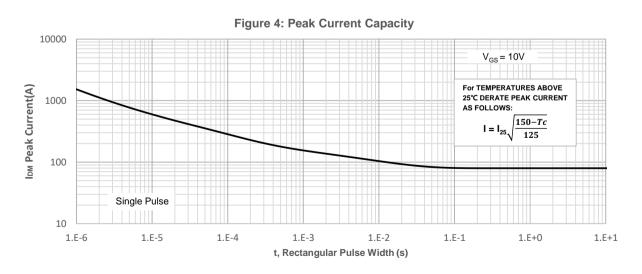


Figure 3: Normalized Maximum Transient Thermal Impedance

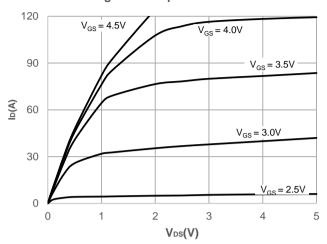






# **Typical Performance Characteristics**

Figure 5: Output Characteristics



**Figure 6: Typical Transfer Characteristics** 

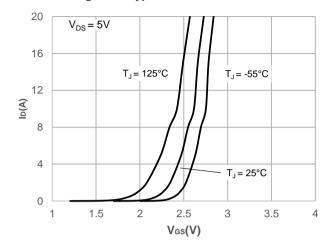


Figure 7: On-resistance vs. Drain Current

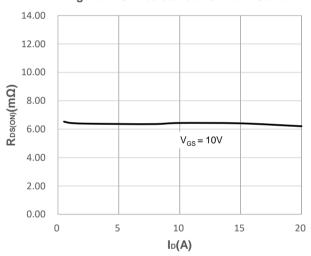


Figure 8: Body Diode Characteristics

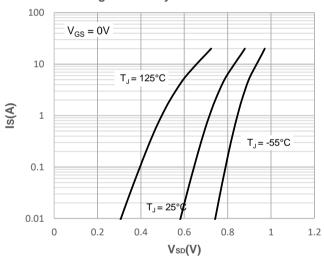
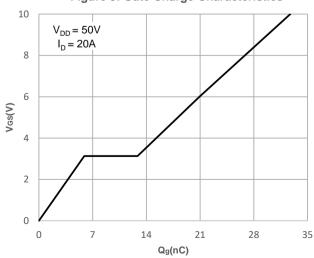
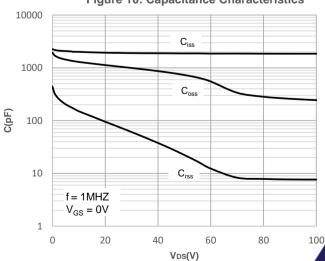


Figure 9: Gate Charge Characteristics



**Figure 10: Capacitance Characteristics** 





# **Typical Performance Characteristics**

Figure 11: Normalized Breakdown voltage vs.
Junction Temperature

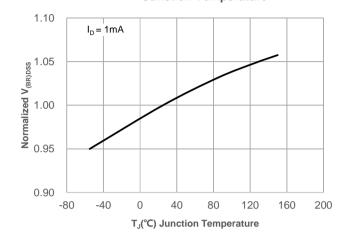


Figure 13: Normalized Threshold Voltage vs.
Junction Temperature

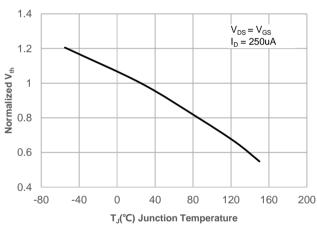


Figure 15: Maximum Safe Operating Area

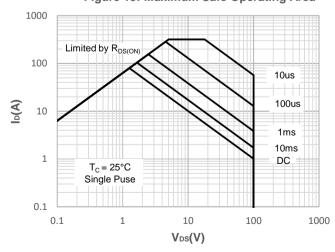
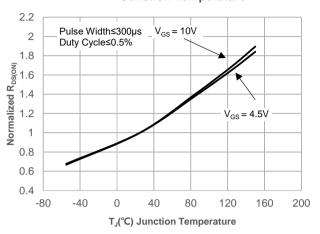
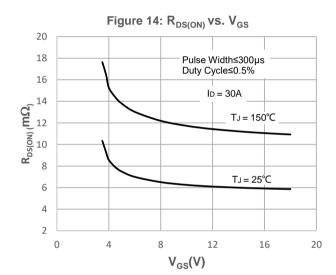


Figure 12: Normalized on Resistance vs.
Junction Temperature







### **Test Circuit**

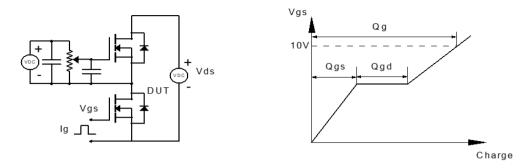


Figure 1: Gate Charge Test Circuit & Waveform

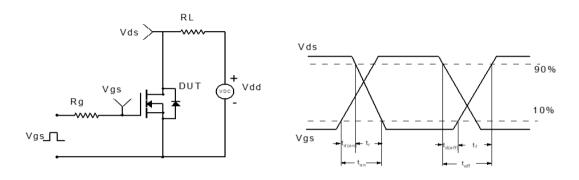


Figure 2: Resistive Switching Test Circuit & Waveform

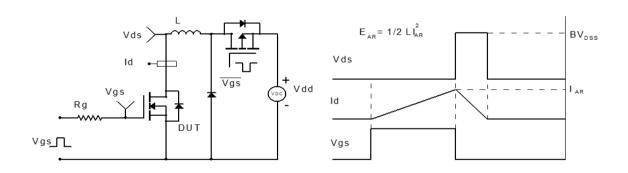


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

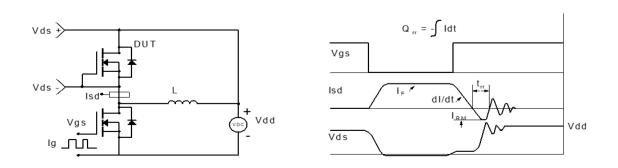
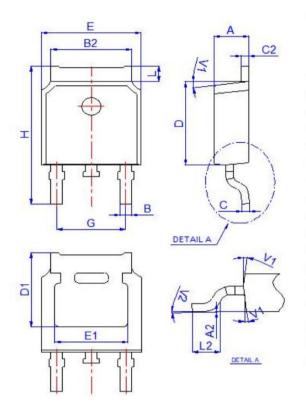


Figure 4: Diode Recovery Test Circuit & Waveform



## Package Mechanical Data(TO-252-3L)



Ref.	Dimensions						
	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1	5.30REF			0.209REF			
E	6.40		6.80	0.252		0.268	
E1	4.63			0.182			
G	4.47		4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.42	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°		6°	

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